

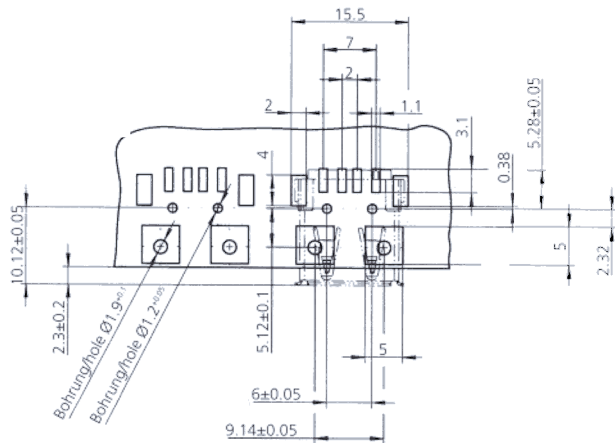
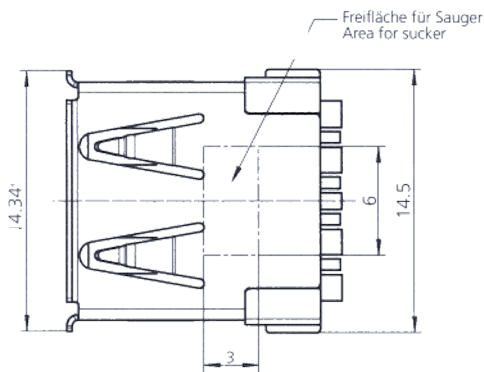
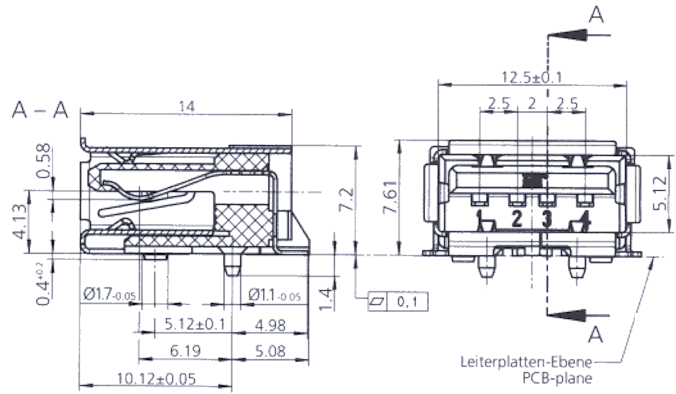
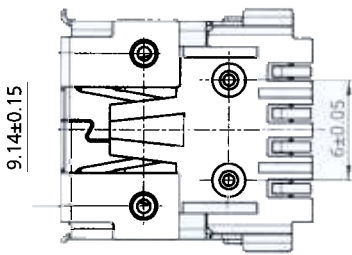
# USB in SMT

## USB Steckverbinder – SMT-Version

## USB Connector – SMT-Version

- USB-Steckverbinder (Type A) in Surface Mount Anschlußtechnik (SMT)
  - Kompatibel mit dem Standard-USB-Steckverbinder
  - Der ODU-USB-Steckverbinder kann durch folgende Verfahren auf die Leiterplatte gelötet werden:
    - Reflow
    - Dampfphase
    - Heißluft
  - Mechanische Kräfte wie bei Durchlötversion
  - **Isolierkörper schwarz**
- USB-Connector (Type A) in Surface Mount Technology (SMT)
  - Compatible with the Standard USB-Connector
  - The ODU-USB-Connector can be soldered to the PCB using:
    - Reflow
    - Vapour Phase
    - Hot Air
  - Mechanical strength like through-solder version
  - **Insulation body black**





| Technische Daten           |                         | Technical Data          |
|----------------------------|-------------------------|-------------------------|
| USB-Serie                  | A                       | USB-Series              |
| Anschlußart                | SMT                     | Soldering               |
| Datenrate                  | 12 Mbs                  | data rate               |
| Übergangswiderstand        | <                       | Termination resistance  |
| Betriebsstrom              | < 1 A                   | Operating current       |
| Steckkraft                 | < 35 N                  | Mating force            |
| Ziehkraft                  | > 10 N                  | Unmating force          |
| Steckzyklen                | > 1500                  | Mating cycles           |
| Temperaturbereich          | - 40°C / + 125°C        | Temperatur rating       |
| Löttemperatur              | < 220° C                | Solder temperatur       |
| Oberfläche                 |                         | Plating                 |
|                            | 1.25 µm Ni + 0.75 µm Au | Contact                 |
|                            | 1.25 µm Ni + 3.0 µm Sn  | Shell                   |
|                            | 1.25 µm Ni + 3.0 µm Sn  | Solder-tail             |
| max. zul. axiale Belastung | F=100 N                 | max. allowed axial Load |